



### SBR3U20SA

3.0A SBR®

# SURFACE MOUNT SUPER BARRIER RECTIFIER SMA

### Product Summary (@ T<sub>A</sub> = +25°C)

Ī	V <sub>RRM</sub> (V)	I <sub>O</sub> (A)	V <sub>F(MAX)</sub> (mV)	I <sub>R(MAX)</sub> (μ <b>A)</b>
	20	3	390	500

### **Features and Benefits**

- Ultra Low Forward Voltage Drop
- Patented Super Barrier Rectifier Technology
- · Soft, Fast Switching Capability
- 150°C Operating Junction Temperature
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

### **Applications**

- SMPS
- DC-DC converter
- · Freewheeling Diodes

### **Mechanical Data**

- Case: SMA
- Case Material: Molded Plastic, "Green" Molding Compound.
   UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Lead-Free Plating (Matte Tin Finish). Solderable per MIL-STD-202, Method 208 (3)
- Polarity Indicator: Cathode Band
- Weight: 0.064 grams (Approximate)







**Bottom View** 

### Ordering Information (Note 4)

Part Number	Case	Packaging
SBR3U20SA-13	SMA	5000/Tape & Reel

Notes:

- 1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.
- See http://www.diodes.com/quality/lead\_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

### **Marking Information**



SQ2,  $S\underline{V}2$  = Product Type Marking Code  $\overline{V}$  = Manufacturer's Code Marking YWW = Date Code Marking Y = Last Digit of Year ex: 7 for 2007 WW = Week Code 01 to 52 XX = Foundry and Assembly



## **Maximum Ratings** @T<sub>A</sub> = +25°C unless otherwise specified

Single phase, half wave, 60Hz, resistive or inductive load.

For capacitance load, derate current by 20%.

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V <sub>RRM</sub> V <sub>RWM</sub> V <sub>RM</sub>	20	V
RMS Reverse Voltage	$V_{R(RMS)}$	14	V
Average Rectified Output Current (See Figure 1)	l <sub>0</sub>	3.0	Α
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I <sub>FSM</sub>	66	А

### **Thermal Characteristics**

Characteristic	Symbol	Value	Unit
Maximum Thermal Resistance Thermal Resistance Junction to Soldering (Note 5) Thermal Resistance Junction to Ambient (Note 6) Thermal Resistance Junction to Ambient (Note 7)	R <sub>0</sub> Js R <sub>0</sub> JA R <sub>0</sub> JA	44 127 97	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-65 to +150	°C

### **Electrical Characteristics** @T<sub>A</sub> = +25°C unless otherwise specified

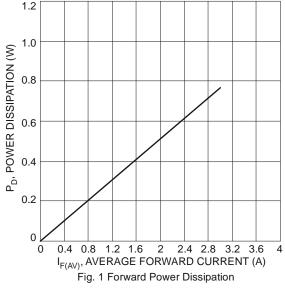
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 8)	$V_{(BR)R}$	20	-	-	V	$I_R = 0.75 \text{mA}$
Forward Voltage Drop	V <sub>F</sub>	- - -	0.26 0.29 0.35 0.28	0.30 0.33 0.39 0.32	V	I <sub>F</sub> = 0.5A, T <sub>J</sub> = +25°C I <sub>F</sub> = 1.0A, T <sub>J</sub> = +25°C I <sub>F</sub> = 3.0A, T <sub>J</sub> = +25°C I <sub>F</sub> = 3.0A, T <sub>J</sub> = +125°C
Leakage Current (Note 8)	I <sub>R</sub>	-	-	500 100	μA mA	$V_R = 20V, T_J = +25$ °C $V_R = 20V, T_J = +125$ °C

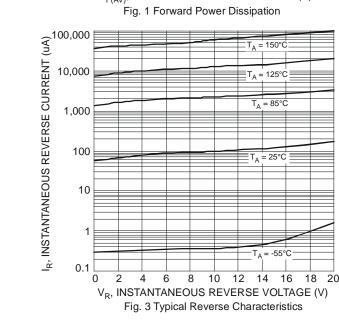
Notes:

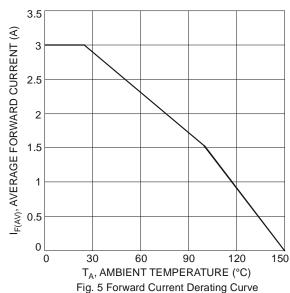
- 5. Theoretical  $R_{\text{0JS}}$  calculated from the top center of the die straight down to the PCB cathode tab solder junction.
- 6. FR-4 PCB, 2 oz. Copper, minimum recommended pad layout per http://www.diodes.com/datasheets/ap02001.pdf, T<sub>A</sub> = +25°C.
- 7. Polymide PCB, 2 oz. Copper, minimum recommended pad layout per http://www.diodes.com/datasheets/ap02001.pdf.
- 8. Short duration pulse test used to minimize self-heating effect.

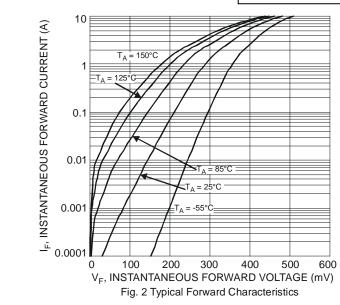


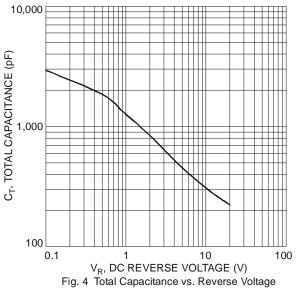


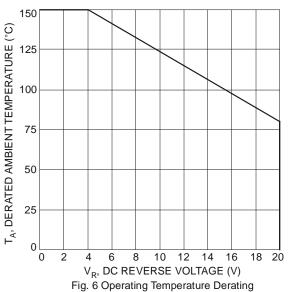








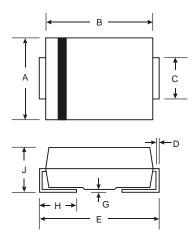






## **Package Outline Dimensions**

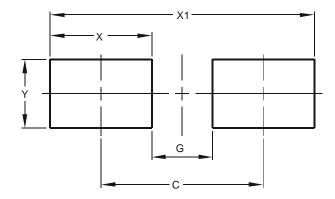
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



SMA					
Dim	Min	Max			
Α	2.29	2.92			
В	4.00	4.60			
С	1.27	1.63			
D	0.15	0.31			
Е	4.80	5.59			
G	0.05	0.20			
Η	0.76	1.52			
7	2.01	2.30			
All Dimensions in mm					

## **Suggested Pad Layout**

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for latest version.



Dimensions	Value (in mm)
C	4.00
G	1.50
Х	2.50
X1	6.50
Υ	1.70



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